

SOT792-1

plastic thermal enhanced low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm; heatsink

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HLQFP44 |
| Package type industry code | HLQFP44 |
| Package style descriptive code | HLQFP (thermal enhanced low profile quad flat package) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MS-026 |
| Mounting method type | S (surface mount) |
| Issue date | 15-11-2002 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-----|------|------|
| D | package length | 9.9 | - | 10 | 10.1 | mm |
| E | package width | 9.9 | - | 10 | 10.1 | mm |
| A | seated height | [tbd] | - | 1.6 | 1.6 | mm |
| A ₂ | package height | 1.35 | - | 1.4 | 1.45 | mm |
| n ₂ | actual quantity of termination | - | - | 44 | - | |

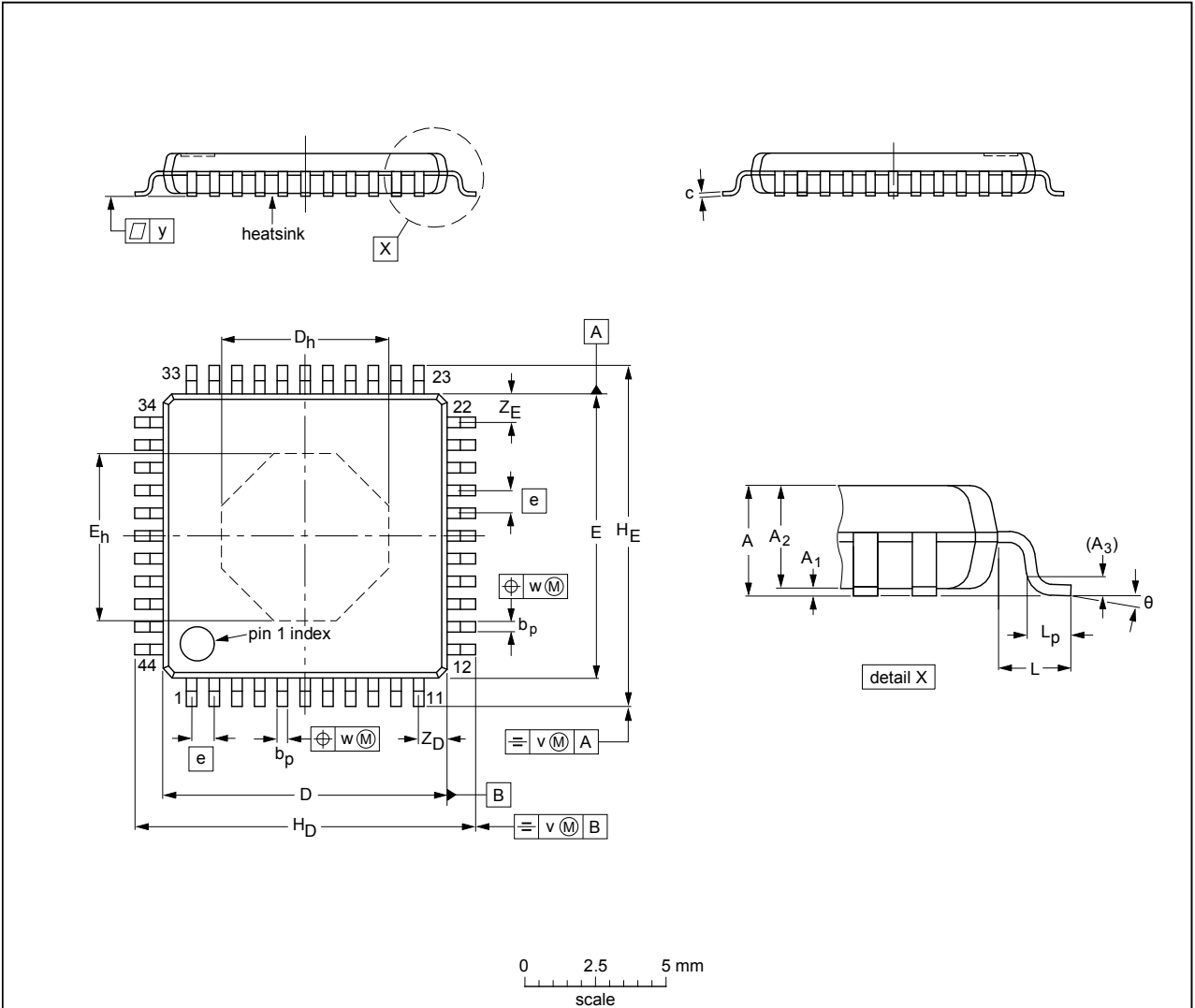


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2. Package outline

HLQFP44: plastic thermal enhanced low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm; heatsink

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DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | H _D | H _E | L | L _p | v | w | y | Z _D ⁽¹⁾ | Z _E ⁽¹⁾ | θ |
|------|--------|----------------|----------------|----------------|----------------|--------------|------------------|----------------|------------------|----------------|-----|----------------|----------------|---|----------------|-----|-----|-----|-------------------------------|-------------------------------|----------|
| mm | 1.6 | 0.15 0.05 | 1.45 1.35 | 0.25 | 0.45 0.30 | 0.20 0.09 | 10.1 9.9 | 6.05 5.75 | 10.1 9.9 | 6.05 5.75 | 0.8 | 12.15 11.85 | 12.15 11.85 | 1 | 0.75 0.45 | 0.2 | 0.2 | 0.1 | 1.2 0.8 | 1.2 0.8 | 7° 0° |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|--------|-------|--|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT792-1 | | MS-026 | | | | 02-11-13 02-11-15 |

Fig. 1. Package outline HLQFP44 (SOT792-1)

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3. Legal information

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4. Contents

| | |
|---------------------------|---|
| 1. Package summary..... | 1 |
| 2. Package outline..... | 2 |
| 3. Legal information..... | 3 |

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